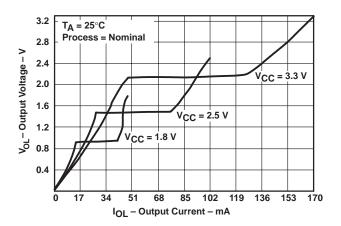
SCES166H - DECEMBER 1998 - REVISED JUNE 2000

- **Member of the Texas Instruments** Widebus™ Family
- **EPIC™** (Enhanced-Performance Implanted **CMOS) Submicron Process**
- **DOC**<sup>™</sup> (Dynamic Output Control) Circuit **Dynamically Changes Output Impedance, Resulting in Noise Reduction Without Speed Degradation**
- **Dynamic Drive Capability Is Equivalent to** Standard Outputs With IOH and IOL of  $\pm$ 24 mA at 2.5-V V<sub>CC</sub>

- Overvoltage-Tolerant Inputs/Outputs Allow Mixed-Voltage-Mode Data Communications
- Ioff Supports Partial-Power-Down Mode Operation
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class I
- Packaged in Thin Shrink Small-Outline **Package**

### description

A Dynamic Output Control (DOC) circuit is implemented, which, during the transition, initially lowers the output impedance to effectively drive the load and, subsequently, raises the impedance to reduce noise. Figure 1 shows typical  $V_{OI}$  vs  $I_{OI}$  and  $V_{OH}$  vs  $I_{OH}$  curves to illustrate the output impedance and drive capability of the circuit. At the beginning of the signal transition, the DOC circuit provides a maximum dynamic drive that is equivalent to a high-drive standard-output device. For more information, refer to the TI application reports, AVC Logic Family Technology and Applications, literature number SCEA006, and Dynamic Output Control (DOC™) Circuitry Technology and Applications, literature number SCEA009.



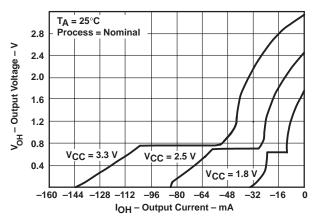


Figure 1. Output Voltage vs Output Current

This 22-bit flip-flop is operational at 1.2-V to 3.6-V V<sub>CC</sub>, but is designed specifically for 1.65-V to 3.6-V V<sub>CC</sub> operation.

The 22 flip-flops of the SN74AVC16722 are edge-triggered D-type flip-flops with clock-enable (CLKEN) input. On the positive transition of the clock (CLK) input, the device stores data into the flip-flops if CLKEN is low. If CLKEN is high, no data is stored.

A buffered output-enable (OE) input places the 22 outputs in either a normal logic state (high or low) or the high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. OE does not affect the internal operation of the flip-flops. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.



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#### description (continued)

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

This device is fully specified for partial-power-down applications using  $I_{off}$ . The  $I_{off}$  circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

The SN74AVC16722 is characterized for operation from -40°C to 85°C.

### terminal assignments

#### **DGG PACKAGE** (TOP VIEW) <u>oe</u> II 64 **∏** CLK Q1 [] 2 63 D1 Q2 [] 3 62 D2 GND ∏ 4 61 ∏ GND Q3 🛮 5 60 D3 Q4 Π 6 59 **D** D4 V<sub>CC</sub> $\square$ 7 58 V<sub>CC</sub> Q5 🛮 8 57 D5 Q6 🛮 9 56 **∏** D6 Q7 [] 10 55 D7 GND [] 11 54 GND Q8 **∏** 12 53 D8 52 D9 Q9 **∏** 13 Q10 14 51 D10 Q11 [] 15 50 D11 Q12 16 49 D12 Q13 17 48 D13 GND [] 18 47 ∏ GND Q14 19 46 D14 Q15 20 45 D15 Q16 21 44 **∏** D16 V<sub>CC</sub> 22 43 V<sub>CC</sub> Q17 23 42 D17 Q18 24 41 **□** D18 GND ∏ 25 40 | GND Q19 **∏** 26 39 D19 Q20 **2**7 38 D20 V<sub>CC</sub> **1** 28 37 V<sub>CC</sub> Q21 [] 29 36 D21 Q22 | 30 35 **□** D22 GND [] 31 34 | GND NC 32 33 CLKEN

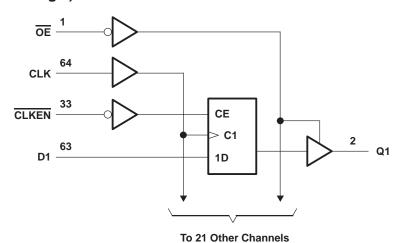
NC - No internal connection



### FUNCTION TABLE (each flip-flop)

	INPL	OUTPUT		
OE	CLKEN	N CLK D		Q
L	Н	Х	Х	Q <sub>0</sub>
L	L	$\uparrow$	Н	Н
L	L	$\uparrow$	L	L
L	L	L or H	Χ	$Q_0$
Н	X	X	Χ	Z

### logic diagram (positive logic)



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V <sub>CC</sub>
Input voltage range, V <sub>I</sub> (see Note 1)
Voltage range applied to any output in the high-impedance or power-off state, VO
(see Note 1)
Voltage range applied to any output in the high or low state, VO
(see Notes 1 and 2)
Input clamp current, $I_{ K }(V_{ C } < 0)$
Output clamp current, $I_{OK}$ ( $V_O < 0$ )
Continuous output current, IO ±50 mA
Continuous current through each V <sub>CC</sub> or GND ±100 mA
Package thermal impedance, θ <sub>JA</sub> (see Note 3)
Storage temperature range, T <sub>Stg</sub> 65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.
  - 2. The output positive-voltage rating may be exceeded up to 4.6 V maximum if the output current rating is observed.
  - 3. The package thermal impedance is calculated in accordance with JESD 51.



### recommended operating conditions (see Note 4)

			MIN	MAX	UNIT			
\/	Cupply voltage	Operating	1.4	3.6	V			
Vcc	Supply voltage	Data retention only	1.2		V			
		V <sub>CC</sub> = 1.2 V	Vcc					
		V <sub>CC</sub> = 1.4 V to 1.6 V	0.65 × V <sub>CC</sub>					
٧ıH	High-level input voltage	$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$	0.65 × V <sub>CC</sub>		V			
		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7					
		V <sub>CC</sub> = 3 V to 3.6 V	2					
		V <sub>CC</sub> = 1.2 V		GND				
	Low-level input voltage	V <sub>CC</sub> = 1.4 V to 1.6 V		0.35 × V <sub>CC</sub>				
$V_{IL}$		$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$		$0.35 \times V_{CC}$	V			
		V <sub>CC</sub> = 2.3 V to 2.7 V		0.7				
		V <sub>CC</sub> = 3 V to 3.6 V		0.8				
٧ <sub>I</sub>	Input voltage		0	3.6	V			
\/o	Output voltage	Active state	0	VCC	V			
VO	Output voltage	3-state	0	3.6	V			
		V <sub>CC</sub> = 1.4 V to 1.6 V		-2				
	Static high-level output current <sup>†</sup>	V <sub>CC</sub> = 1.65 V to 1.95 V		-4	mA			
IOHS		$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		-8	mA			
		$V_{CC} = 3 \text{ V to } 3.6 \text{ V}$		-12				
		V <sub>CC</sub> = 1.4 V to 1.6 V		2				
1-1-	Static law level output ourrent	V <sub>CC</sub> = 1.65 V to 1.95 V		4	^			
lors	Static low-level output current <sup>†</sup>	V <sub>CC</sub> = 2.3 V to 2.7 V		8	mA			
		V <sub>CC</sub> = 3 V to 3.6 V		12	1			
Δt/Δν	Input transition rise or fall rate	V <sub>CC</sub> = 1.4 V to 3.6 V		5	ns/V			
TA	Operating free-air temperature	•	-40	85	°C			

<sup>†</sup> Dynamic drive capability is equivalent to standard outputs with IOH and IOL of ±24 mA at 2.5-V VCC. See Figure 1 for VOL vs IOL and VOH vs IOH characteristics. Refer to the TI application reports, AVC Logic Family Technology and Applications, literature number SCEA006, and Dynamic Output Control (DOC™) Circuitry Technology and Applications, literature number SCEA009.

NOTE 4: All unused inputs of the device must be held at VCC or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

	PARAMETER	TEST (	CONDITIONS	VCC	MIN	TYP	MAX	UNIT	
		I <sub>OHS</sub> = -100 μA		1.4 V to 3.6 V	V <sub>CC</sub> -0.2				
		$I_{OHS} = -2 \text{ mA},$	V <sub>IH</sub> = 0.91 V	1.4 V	1.05				
Vон		$I_{OHS} = -4 \text{ mA},$	V <sub>IH</sub> = 1.07 V	1.65 V	1.2			V	
		$I_{OHS} = -8 \text{ mA},$	V <sub>IH</sub> = 1.7 V	2.3 V	1.75				
		$I_{OHS} = -12 \text{ mA},$	V <sub>IH</sub> = 2 V	3 V	2.3				
		I <sub>OLS</sub> = 100 μA		1.4 V to 3.6 V			0.2		
		$I_{OLS} = 2 \text{ mA},$	V <sub>IL</sub> = 0.49 V	1.4 V			0.4		
VOL		$I_{OLS} = 4 \text{ mA},$	V <sub>IL</sub> = 0.57 V	1.65 V			0.45	V	
		$I_{OLS} = 8 \text{ mA},$	$V_{IL} = 0.7 V$	2.3 V			0.55		
		$I_{OLS} = 12 \text{ mA},$	$V_{IL} = 0.8 V$	3 V			0.7		
П		$V_I = V_{CC}$ or GND		3.6 V			±2.5	μΑ	
l <sub>off</sub>		$V_I$ or $V_O = 3.6 V$		0			±10	μΑ	
loz		$V_O = V_{CC}$ or GND		3.6 V			±10	μΑ	
Icc		$V_I = V_{CC}$ or GND,	IO = 0	3.6 V			40	μΑ	
	Control inputs			2.5 V		4			
C.	Control inputs	$V_{I} = V_{CC}$ or GND		3.3 V		4		ا ا	
Ci	Data inputs	Al = ACC or GIAD		2.5 V		2		pF	
				3.3 V		2			
	Outputs	V V CVD		2.5 V		6.5		n.E	
Co	Outputs	AQ = ACC OLGIND	VO = VCC or GND			6		pF	

<sup>†</sup> Typical values are measured at  $T_A = 25$ °C.

# timing requirements over recommended operating free-air temperature range (unless otherwise noted) (see Figures 2 through 5)

			V <sub>CC</sub> = 1.2 V		V <sub>CC</sub> = 1.5 V ± 0.1 V		V <sub>CC</sub> = 1.8 V ± 0.15 V		V <sub>CC</sub> = 2.5 V ± 0.2 V		V <sub>CC</sub> = 3.3 V ± 0.3 V		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
fclock	Clock frequency							80		140		175	MHz
t <sub>W</sub>	Pulse durati	on, CLK high or low					6.2		3.5		2.8		ns
	t <sub>SU</sub> Setup time	Data before CLK↑	12.8		8.3		5.7		3.5		2.5		20
<sup>L</sup> SU		CLKEN before CLK↑	3.5		2		1.6		1.4		1.4		ns
4.	Hold time	Data after CLK↑			0	·	0		0		0		20
t <sub>h</sub>	noia time	CLKEN after CLK↑	2.1		1.6		1.3		1.2		1.2		ns

## switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figures 2 through 5)

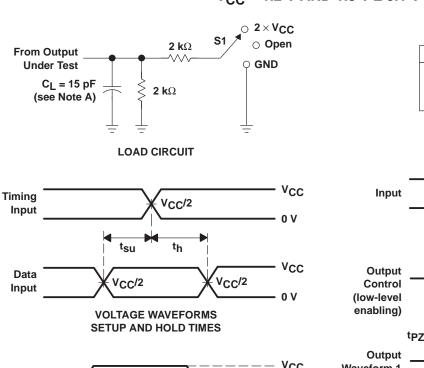
PARAMETER	FROM TO (INPUT)		V <sub>CC</sub> = 1.2 V	V <sub>CC</sub> = 1.5 V ± 0.1 V		V <sub>CC</sub> = 1.8 V ± 0.15 V		V <sub>CC</sub> = 2.5 V ± 0.2 V		V <sub>CC</sub> = 3.3 V ± 0.3 V		UNIT
	(INFOT)	(0011-01)	TYP	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
f <sub>max</sub>							80		140		175	MHz
t <sub>pd</sub>	CLK	Q	7.7	1.5	6.3	1.5	5.4	1	3.3	0.7	2.6	ns
t <sub>en</sub>	ŌĒ	Q	11.2	2.5	10.6	2.4	9.5	1.8	6	1.4	4.3	ns
t <sub>dis</sub>	ŌĒ	Q	6.8	1.9	7.2	1.9	7	1.2	3.6	1.2	3.4	ns

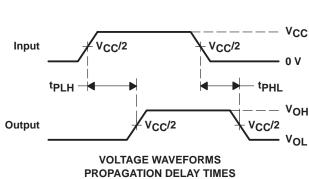


### operating characteristics, T<sub>A</sub> = 25°C

PARAMETER			TEST CONDITIONS	V <sub>CC</sub> = 1.8 V	$V_{CC} = 2.5 \text{ V}$	$V_{CC} = 3.3 \text{ V}$	UNIT	
FARAMETER		TEST CONDITIONS	TYP	TYP	TYP	ONII		
<u> </u>	Power dissipation	Outputs enabled	C <sub>1</sub> = 0, f = 10 MHz	88	98	110	n.E	
<sup>Cpd</sup> capacitance	capacitance	Outputs disabled	$C_L = 0$ , $f = 10 \text{ MHz}$	60	64	79	p⊦	

## PARAMETER MEASUREMENT INFORMATION $V_{CC}$ = 1.2 V AND 1.5 V $\pm$ 0.1 V





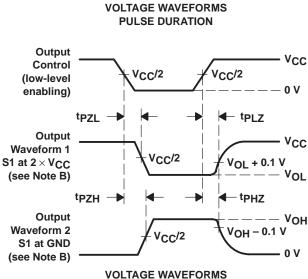


V<sub>CC</sub>/2

VCC

. 0 V

V<sub>CC</sub>/2



**ENABLE AND DISABLE TIMES** 

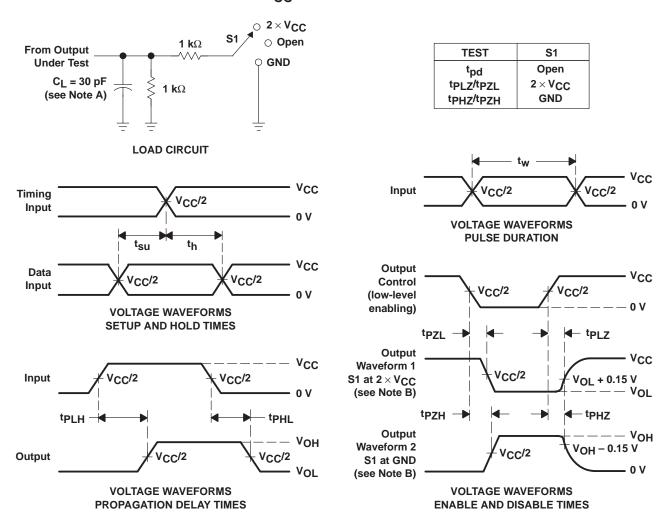
NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz, Z  $_{\mbox{O}}$  = 50  $\Omega$ ,  $t_{\mbox{f}}$   $\leq$  2 ns.  $t_{\mbox{f}}$   $\leq$  2 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpZL and tpZH are the same as ten.
- G. tplH and tpHL are the same as tpd.

Figure 2. Load Circuit and Voltage Waveforms



## PARAMETER MEASUREMENT INFORMATION $V_{CC} = 1.8 \text{ V} \pm 0.15 \text{ V}$

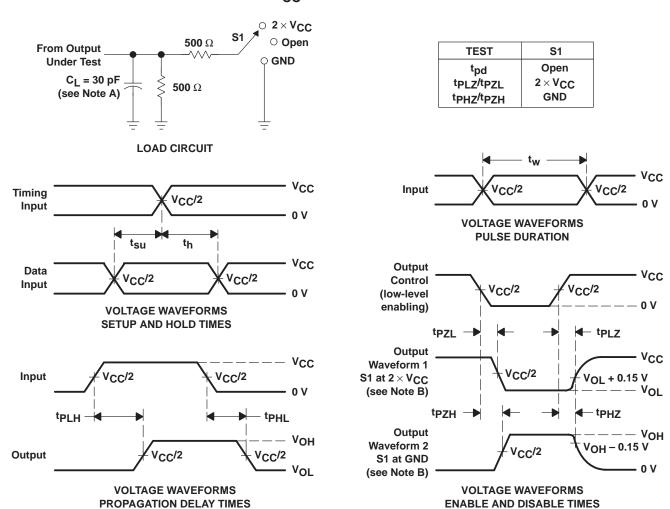


NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \Omega$ ,  $t_f \leq 2$  ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.

Figure 3. Load Circuit and Voltage Waveforms

## PARAMETER MEASUREMENT INFORMATION $V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$

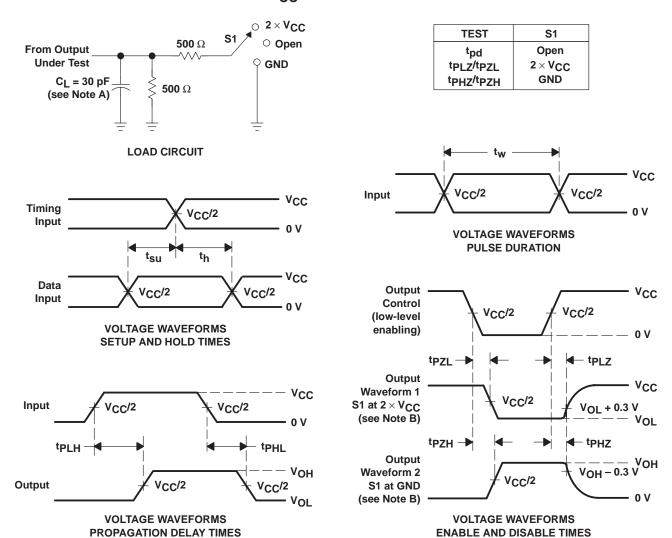


- NOTES: A. C<sub>I</sub> includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
  - C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_Q = 50 \Omega$ ,  $t_f \leq$  2 ns,  $t_f \leq$  2 ns.
  - D. The outputs are measured one at a time with one transition per measurement.
  - E. tpLz and tpHz are the same as tdis.
  - F. tpzL and tpzH are the same as ten.
  - G. tpLH and tpHL are the same as tpd.

Figure 4. Load Circuit and Voltage Waveforms



### PARAMETER MEASUREMENT INFORMATION $V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$



- NOTES: A. C<sub>I</sub> includes probe and jig capacitance.
  - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
  - C. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \Omega$ ,  $t_f \leq$  2 ns,  $t_f \leq$  2 ns.
  - D. The outputs are measured one at a time with one transition per measurement.
  - E. tpl 7 and tpH7 are the same as tdis.
  - F. tpzL and tpzH are the same as ten.
  - G. tplH and tpHL are the same as tpd.

Figure 5. Load Circuit and Voltage Waveforms



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